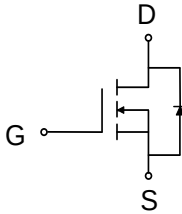
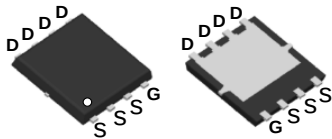


N-Channel Advanced Trench MOSFET

MSR007N03D33

PDFN3.3*3.3



Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

Applications

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Maximum ratings, at $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter		Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage		30	V
V_{GS}	Gate-Source voltage		± 20	V
I_D	Continuous drain current	$T_C = 25^\circ\text{C}$	35	A
		$T_C = 100^\circ\text{C}$	23	A
I_{DM}	Pulse drain current tested	$T_C = 25^\circ\text{C}$	100	A
EAS	Avalanche energy, single pulsed ($L=0.1\text{mH}$)		64	mJ
PD	Maximum power dissipation	$T_C = 25^\circ\text{C}$	25	W
T_{STG}, T_J	Storage and Junction Temperature Range		-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Rating	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	5	°C/W

Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
--------	-----------	-----------	------	------	------	------

Static Electrical Characteristics @T_j=25°C (unless otherwise stated)

V(BR) _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	30	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V	--	--	1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.7	2.2	V
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =10A	--	5.5	7	mΩ
		V _{GS} =4.5V, I _D =5A	--	8.5	12	mΩ

Dynamic Electrical Characteristics@T_j = 25°C (unless otherwise stated)

C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V , f=1MHz	--	950	--	pF
C _{oss}	Output Capacitance		--	130	--	pF
C _{rss}	Reverse Transfer Capacitance		--	108	--	pF
Q _g	Total Gate Charge	V _{DS} =15V, I _D =10A , V _{GS} =10V	--	22	--	nC
Q _{gs}	Gate-Source Charge		--	2.7	--	nC
Q _{gd}	Gate-Drain Charge		--	5	--	nC

Switching Characteristics

Td(on)	Turn-on Delay Time	V _{DD} =15V V _{GS} =10V I _D =2A R _L =1Ω R _G =3Ω	--	10	--	ns
Tr	Turn-on Rise Time		--	8	--	ns
Td(off)	Turn-Off Delay Time		--	30	--	ns
Tf	Turn-Off Fall Time		--	5	--	ns

Source- Drain Diode Characteristics@ T_j = 25°C (unless otherwise stated)

VSD	Forward on voltage	I _S =1A, V _{GS} =0V	--	--	1.2	V
I _S	Diode Forward Current		--	--	35	A

Typical Characteristics

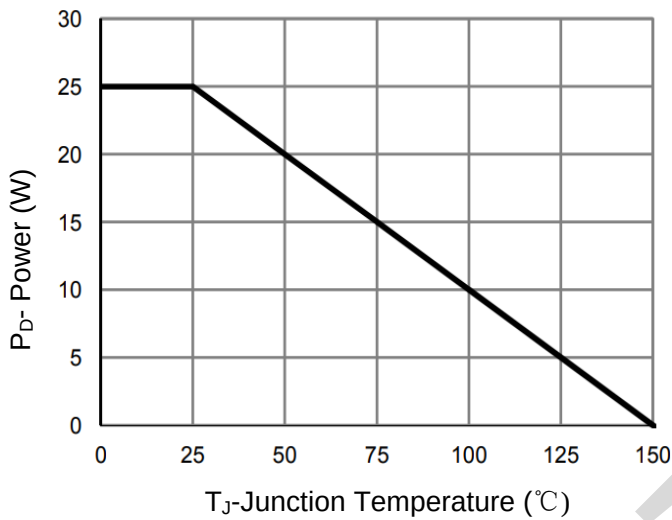


Figure 1 Power De-rating

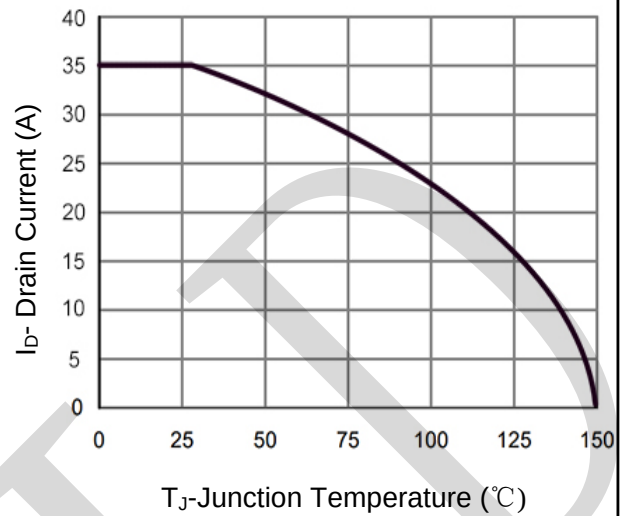


Figure 2 Drain Current

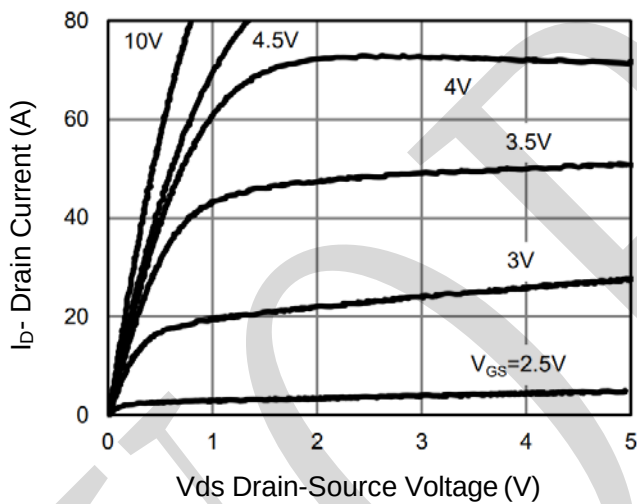


Figure 3 Output Characteristics

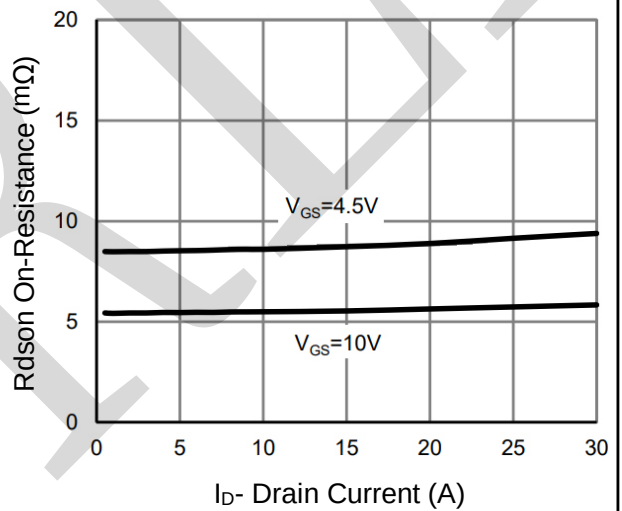


Figure 4 $R_{DS(on)}$ vs Drain Current

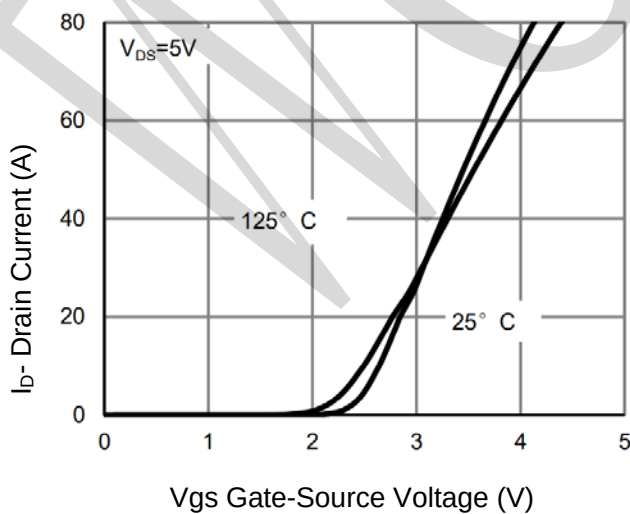


Figure 5 Transfer Characteristics

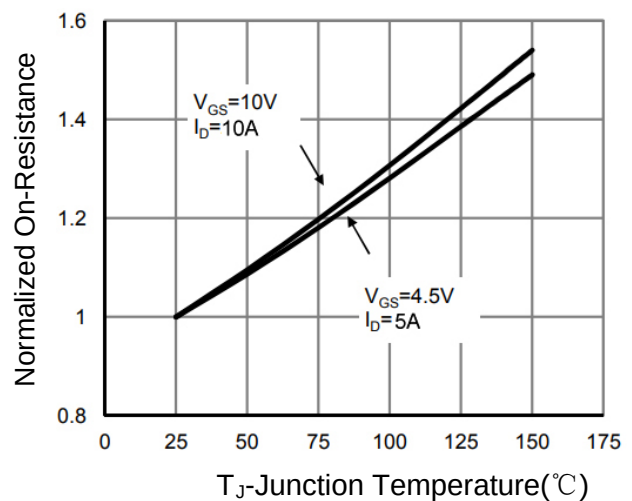


Figure 6 $R_{DS(on)}$ vs Junction Temperature

Typical Characteristics

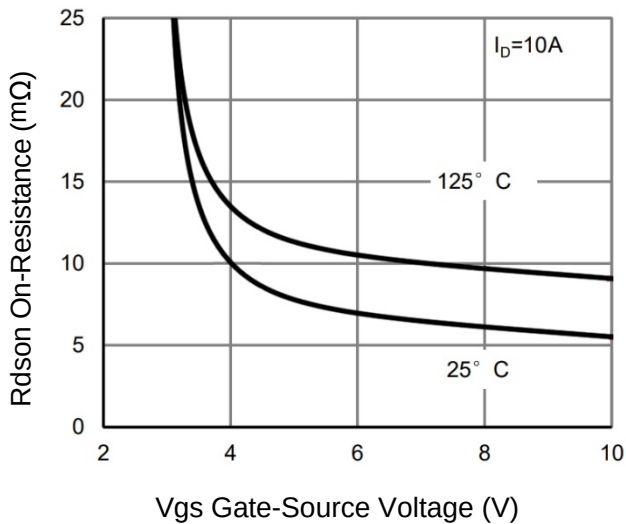


Figure 7 Rdson vs Vgs

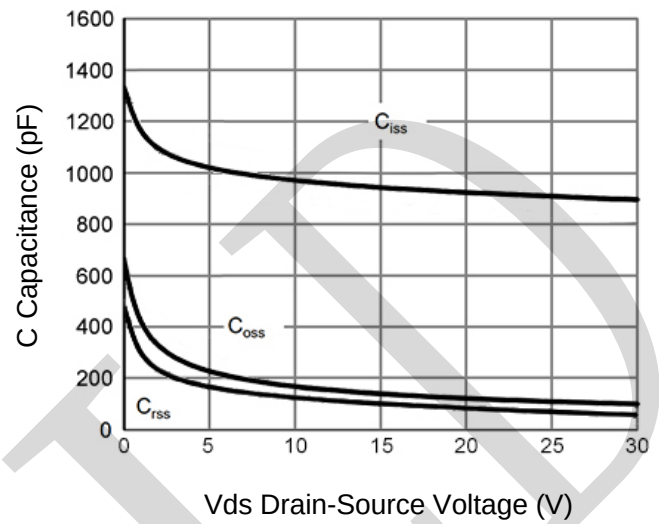


Figure 8 Capacitance vs Vds

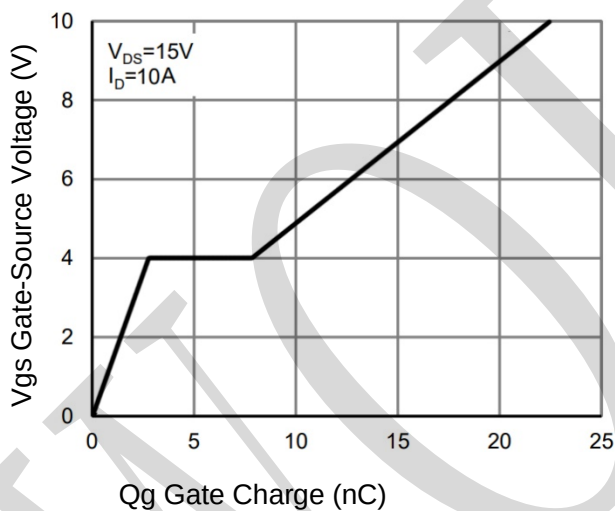


Figure 9 Gate Charge

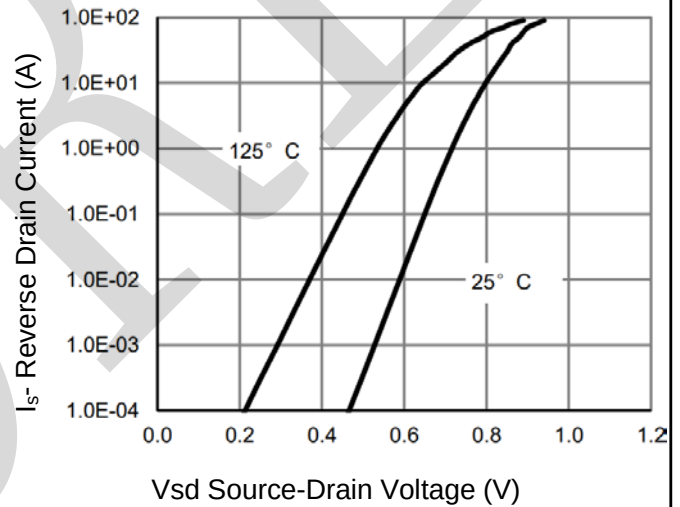


Figure 10 Source- Drain Diode Forward

Typical Characteristics

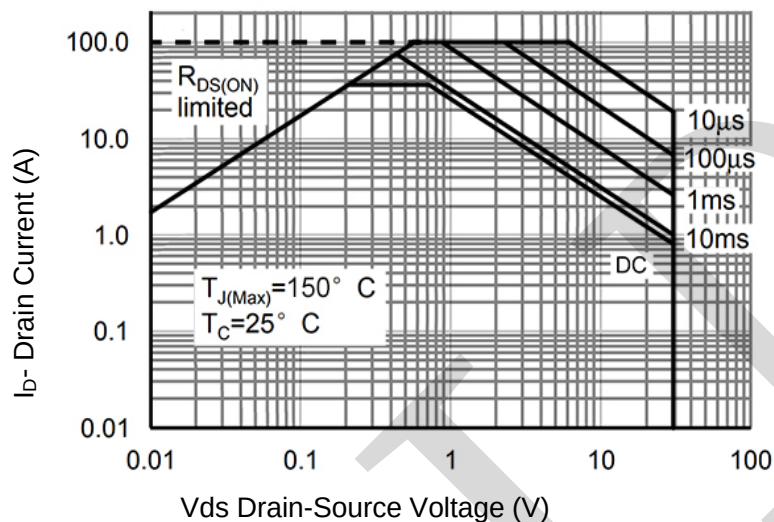


Figure 11 Safe Operation Area

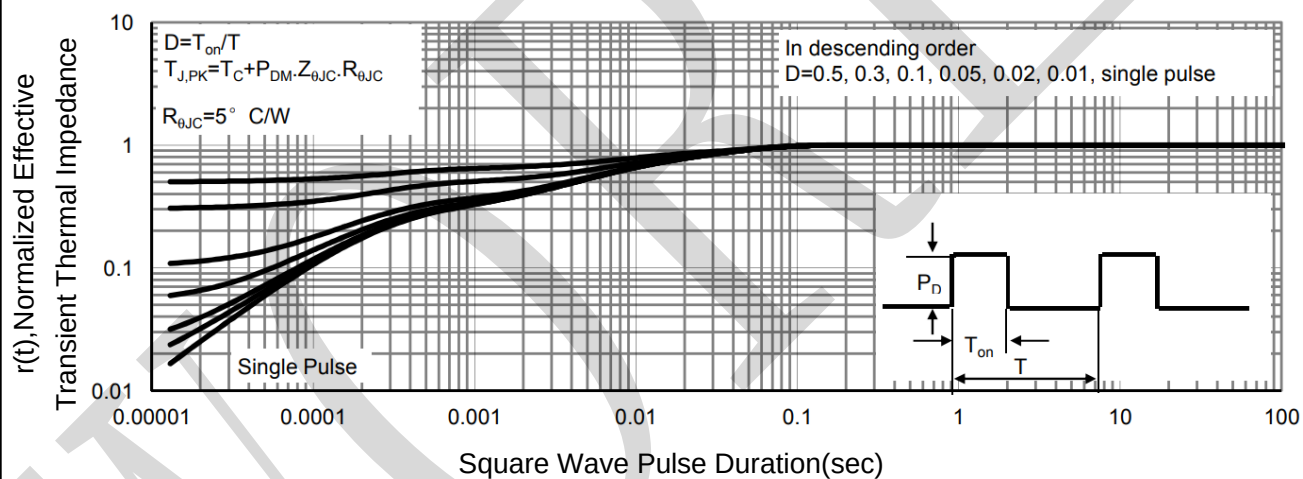
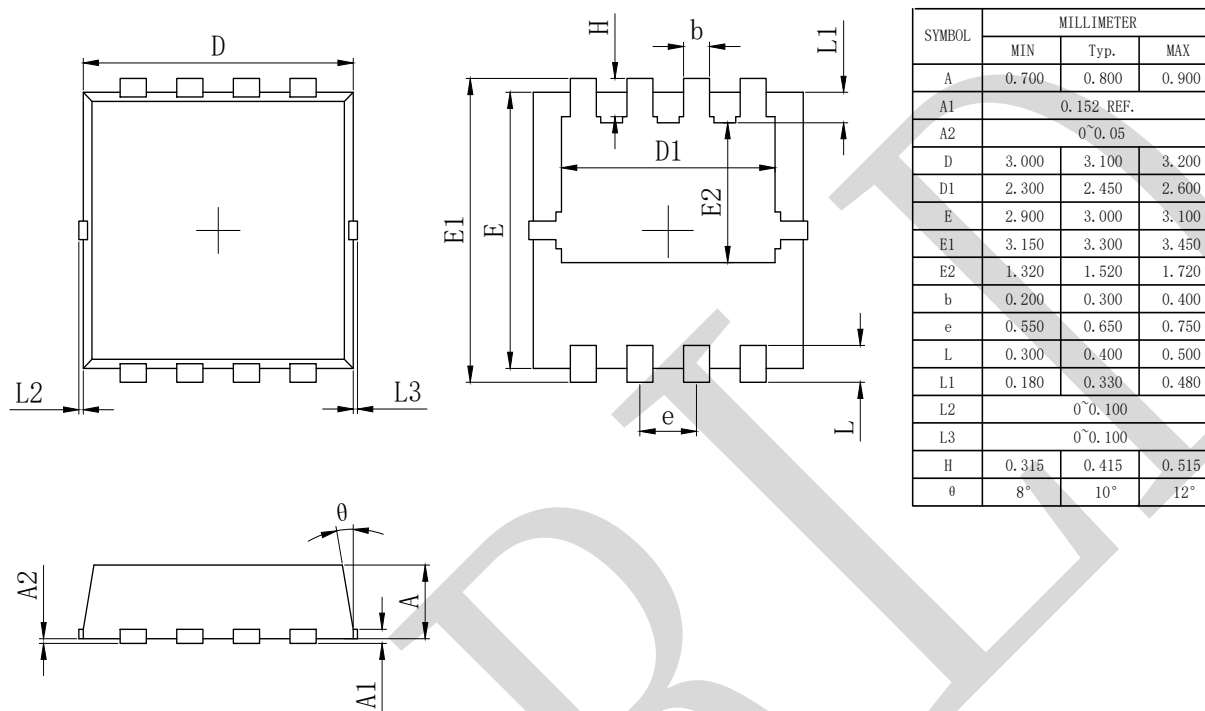


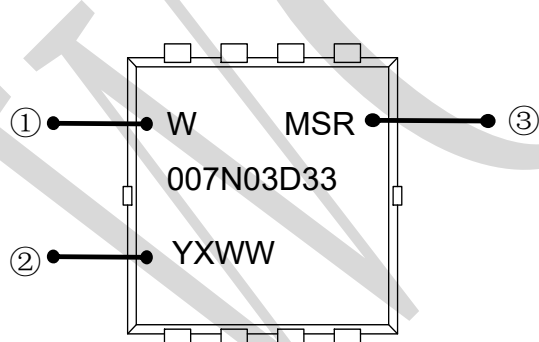
Figure 12 Normalized Maximum Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS

PDFN3.3*3.3



Marking Information



- ① W : Company's trademark
- ② Product model : MSR007N03D33
- ③ PDC information :

Y X WW

WW:Week code(01 to 53)

X:Internal identification code

Y:Year code(ex:0=2020)